

L Number	Hits	Search Text	DB	Time stamp
1	314708	integrated near1 circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:47
2	1053	passive\$1 and substrate\$1 and layer\$1 and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:53
3	669	(integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:52
4	26629	substrate\$1 and layer\$1 and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:52
5	20785	inductor\$1 and capacitor\$1 and transistor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:54
6	37150	passive\$1 and active\$1 and element\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 17:55
7	34	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (inductor\$1 and capacitor\$1 and transistor\$1) and (passive\$1 and active\$1 and element\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 18:52
8	467	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 18:52
9	250	257/528.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:24
10	4	((((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/528.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:24
11	383	257/531.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:29
12	7	((((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/531.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:29
13	1381	257/532.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:32

14	467	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and (integrated near1 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:29
15	8	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/532.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:32
16	137	257/535.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:33
17	2	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/535.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:33
18	1122	257/536.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:33
19	3	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/536.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:33
20	373	257/537.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:34
21	3	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/537.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:34
22	468	257/538.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:34
23	2	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/538.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:34
24	97	257/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:37
25	2	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/549.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:38
26	111	438/6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:02
27	151968	257/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:38

28	189	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:01
29	71	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/\$7.ccls.) and interconnect\$4 with layer\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 19:39
30	63	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 257/\$7.ccls.) and interconnect\$4 with layer\$1) and @ad<=20010417	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:00
31	3	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:02
32	734	438/238.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:06
33	9	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/238.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:06
34	541	438/239.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:09
35	2	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/239.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:09
36	436	438/241.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:10
37	1	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/241.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:10
38	105	438/242.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:11
39	6	((integrated nearl circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/242.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:11
40	345	438/243.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:12

41	4	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/243.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:12
42	212	438/244.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:14
43	3	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/244.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:14
44	55	438/245.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:15
45	2	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/245.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:16
46	111	438/248.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:15
47	2	((integrated near1 circuit) and (passive\$1 and substrate\$1 and layer\$1 and trench)) and (substrate\$1 and layer\$1 and trench) and (passive\$1 and active\$1 and element\$1)) and 438/248.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/26 20:16